

OKA-C104

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith for filing is the (X) utility, () design, () plant patent application of:

INVENTORS: Taizo OKU, Junichi AOKI, Youichi YAMAMOTO,
Takashi KOROMOKAWA and Kazuo MAEDA

FOR: FILM FORMING METHOD, SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR DEVICE MANUFACTURING METHOD

Enclosed are:

(X) 56 pages of specification

(X) Abstract

(X) Oath or Declaration

(X) Power of Attorney

18 Sheets of (X) formal () informal drawings

(X) An assignment of the application to: CANON SALES CO., INC. and
SEMICONDUCTOR PROCESS LABORATORY CO., LTD.

(X) Preliminary Amendment

() Information Disclosure Statement

() Change of Address

(X) Assignment Cover Sheet

() Petition to Make Special Under 37 CFR 1.102(c)

() Applicant is entitled to Small Entity Status

The filing fee is calculated as follows:

Basic Fee	Number Filed	Number Extra	Large Entity	Small Entity	Amount
Utility	XXX	XXX	\$ 710.00	\$ 355.00	\$ 710.00
Design	XXX	XXX	\$ 310.00	\$ 155.00	
Plant	XXX	XXX	\$ 480.00	\$ 240.00	
Total	18- 20 =	0	x \$18.00	X \$9.00	
Independent Claims	3 -3 =	0	x \$80.00	x \$ 40.00	
Multiple Dependency			\$ 260.00	\$ 130.00	
Late Fee Surcharge			\$ 130.00	\$ 65.00	
Assignment Recordation			\$ 40.00		40.00
TOTAL FEE					\$ 750.00

☐ A check in the amount of \$.00 to cover the filing fee is enclosed.

☒ A credit card payment form for the \$ 750.00 fee is enclosed herewith.

☐ Please charge Deposit Account No. in the amount of

☐ This application is filed under the provisions of 37 CFR 1.53, and does not include:

☐ Oath or Declaration

☐ Filing Fee

☒ The Commissioner is hereby authorized to charge payment of the following fees or credit any overpayment to Deposit Account No. 12-2174. A duplicate copy of this sheet is enclosed.

☒ Any additional filing fees required under 37 CFR 1.16.

☒ Any patent application processing fees under 37 CFR 1.17.

☐ The Issue Fee set in 37 CFR 1.18 at or before mailing of the Notice of Allowance, pursuant to 37 CFR 1.311(b).

(X) Priority is claimed under 35 USC 119 based on the following:

<u>Serial No.</u>	<u>Country</u>	<u>Date</u>
2000-221379	Japan	21/07/2000
2000-281263	Japan	18/09/2000

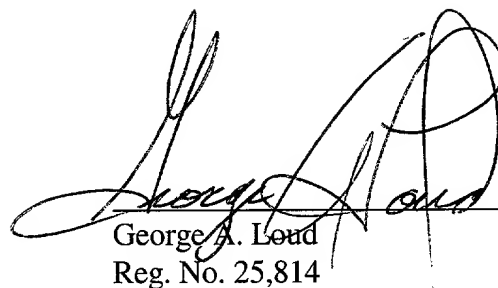
(X) Certified copies enclosed.

() Priority is claimed under 35 USC 119(e) based on the following U.S. Provisional Application:

<u>Serial No.</u>	<u>Filing Date</u>
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() Priority is claimed under 35 USC 120 based on the following:

<u>Serial No.</u>	<u>Filing Date</u>	<u>Status</u>
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George A. Loud
Reg. No. 25,814

Dated: July 13, 2001

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3137 Mount Vernon Avenue
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

OKU et al

Serial No.:

Filed: July 13, 2001

For: FILM FORMING METHOD, SEMICONDUCTOR
DEVICE AND SEMICONDUCTOR DEVICE
MANUFACTURING METHOD

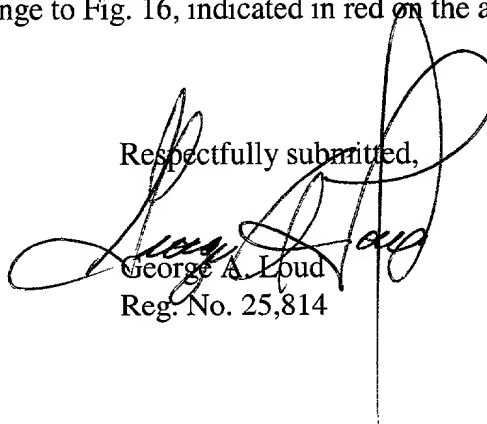
REQUEST FOR APPROVAL OF DRAWING CHANGE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The examiner's approval of the change to Fig. 16, indicated in red on the attached, is
respectfully requested.

Respectfully submitted,



George A. Loud
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